

SEMICONDUCTOR INTEGRATED CIRCUIT CARD MANUFACTURING METHOD,
AND SEMICONDUCTOR INTEGRATED CIRCUIT CARD

ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit card is disclosed in which such a semiconductor integrated circuit chip device comprising a substrate having a circuit pattern formed thereon, a semiconductor circuit chip bonded onto the substrate and having an electrode connected to the circuit pattern, a reinforcement metal plate, and a seal resin portion for covering a peripheral face of the semiconductor integrated circuit chip and sticking the reinforcement metal plate onto the semiconductor integrated circuit chip is mounted within a card substrate.

Figure 3

This Sheet Has Been Replaced

